



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2022-09-07
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	Antonella Lanzafame	Representative title	AMSMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
TS27L4IDT	CDK7*27L4AAW	A	BO2A	2022-09-07
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	130.00	mg	Each	ECOPACK® 3

Manufacturing information			
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles	
1	260	3	
Bulk solder termination	Terminal plating	Terminal base alloy	Comment
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	,



QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020		Response
1 - Product(s) meets EU ELV requirements without any exemptions		true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
Exemption Id.	Description	

QueryList : California Prop65 list, dated 25th Feb 2022			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			true
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			false
Substance	amount in product (mg)	Application	ppm in product

QueryList : REACH-10 Jun 2022				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
	#N/A			
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material
	#N/A			

QueryList : Responsible metals sourcing		Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.		true
The following metals are present is the component :		Tin,

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020		Response
The product contains adhesives identified under GB 33372		true
All the adhesive impacted complies with GB 33372		true

Stockholm Convention Persistent Organic Pollutants		Response
Product is compliant with Stockholm Convention Persistent Organic Pollutants Annex I		false



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	CDK7'27L4AAW		130.0000		4999998.0	1000001.0
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	2.288	mg	supplier	die	Silicon(Si)	7440-21-3		2.231	mg	975087	17162
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.009	mg	3934	69
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.006	mg	2622	46
				supplier	passivation	Silicon oxide	7631-86-9		0.042	mg	18357	323
				supplier	metallization	Silver (Ag)	7440-22-4		0.172	mg	4922	1323
Leadframe	M-004 Copper and its alloys	34.945	mg	supplier	alloy	Copper(Cu)	7440-50-8		33.886	mg	969695	260662
				supplier	alloy	Iron(Fe)	7439-89-6		0.797	mg	22807	6131
				supplier	alloy	Iron phosphide	1310-43-6		0.048	mg	1374	369
				supplier	alloy	Zinc(Zn)	7440-66-6		0.042	mg	1202	323
				supplier	metallization	Silver (Ag)	7440-22-4		0.172	mg	4922	1323
Die attach	M-011 Other inorganic materials	0.402	mg	supplier	glue	Silver(Ag)	7440-22-4	0	0.354	mg	880597	2723
				supplier	glue	Isobornyl methacrylate	7534-94-3		0.020	mg	49751	154
				supplier	glue	Isobornyl acrylate	5888-33-5		0.020	mg	49751	154
				supplier	glue	Methyl acrylate polymer	87320-05-6		0.008	mg	19900	62
				supplier	glue	Silver(Ag)	7440-22-4		0.354	mg	880597	2723
Encapsulation	M-011 Other inorganic materials	91.107	mg	supplier	mold compound	Silica vitreous	60676-86-0		65.233	mg	716004	501792
				supplier	mold compound	Silicon oxide	7631-86-9		13.666	mg	149999	105123
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		6.833	mg	75000	52562
				supplier	mold compound	Phenol resin	26834-02-6		4.555	mg	49996	35038
				supplier	mold compound	Carbon black	1333-86-4		0.456	mg	5005	3508
Connections coating	Solder	1.258	mg	supplier	mold compound	Bismuth compound	7440-69-9		0.364	mg	3995	2800
				supplier	solder alloy	Tin (Sn)	7440-31-5		1.258	mg	1000000	9677